Product End-of-Life Disassembly Instructions

Product Category: Storage Enclosures
Marketing Name / Model [List multiple models if applicable.]
HP EVA4400 Dual controller Array W/Switch / AG805A
HP EVA4400 Dual Cntrl w/8Gb SFP Switch / AG805B
HP EVA4400 Dual controller Array W/Switch / AG805C
HP EVA4400 Dual Controller Array / AG637A
HP EVA4400 Dual Controller Array / AG637B

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm (AG637x) = (AG805x) =	21 25
Batteries	All types including standard alkaline and lithium coin or button style batteries (AG637x) = (AG805x) =	2 4
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		4
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Screw Drivers	T-15
Phillips Screw Driver	#2
Flat head Screw Driver	Medium

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove top cover by loosening the thumb screw at the rear of the enclosure. A T-15 may be used for removal. Slide the top cover back approximately 3cm's and lift the top cover off/
2. Remove the front UID assembly from the chassis by pulling out the 2 retaining plungers and pulling the circuit board directly backwards. See figure 1.
3. Disconnect the UID flex assembly from the Midplane on the inside of the chassis from the connector. Lift the top of the connector to unlock before removal of the flex. See figure 2.
4. Remove the rear UID bezel, circuit board and flex assembly. First remove the flex assembly from the vertical riser assembly which is connected to the Midplane. Then remove the retaining screw holding the PCA and rear bezel in place. Finish by removing the PCA and rear bezel. See figure 3.
5. Remove both batteries from the front of the enclosure by pulling on the rose colored handles. Remove the sheet metal to reveal the Lithium Ion battery pack which needs to be recycled. See figure 4.
6. Remove the screws as shown in figure 5 & 6 and slide top cover off.
7. Remove battery connectors and PCA from sheet metal. See figure 7 and 8.
8. Slide battery pack out, Open the plastic case holding the batteries by prying open the case with a flat head screw driver. Pry open on all 3 sides of the case. Dispose of the batteries according to local recycling guidelines. See figure 9 & 10.
9. Remove the 2 fans from the front of the enclosure by using the rose colored handles. Remove PCA by removing the 3 Phillips head screws and 2 connectors from the PCA. See figure 11 :
10. Remove the TBM card from the back of the enclosure. Remove the main PCA by removing the 6 Phillips head screws. The Smaller PCA can be removed by pulling on the tabs on the side of the connector. See figure 12:
11. AG805x only: Remove the 2 controllers/switches form the enclosure. Depress the tab on the top cover and remove. Each controller has a battery which must be disposed of according to local recycling guidelines. See figure 13.
12. Remove the riser assembly by pulling straight up. See figure 14.
13. Remove the power supplies, open sheet metal by removing the Phillips head screws, and remove the 2 electrolytic capacitors on each power supply. (2 on each supply). See figures 15 and 16.
14. AG637x only: Remove controllers from the front of the enclosure. Depress the tab and slide the top cover off. Remove the Phillips head retaining screws on the top and bottom of the sheet metal to remove the 2 PCA's from each controller. See figure 17 & 18.
15. Remove Midplane by first removing all items which connect to the Midplane as noted above. Remove the brackets on each side by removing the thumb screws. Remove the 9 Phillips screws, tilt the Midplane and remove. See figure 19.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1.

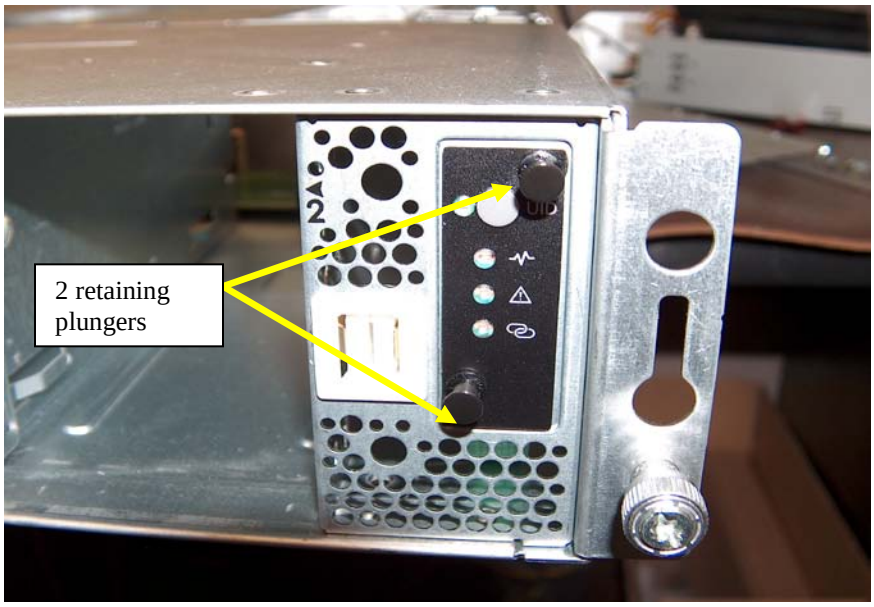


Figure 2.

Figure 3.

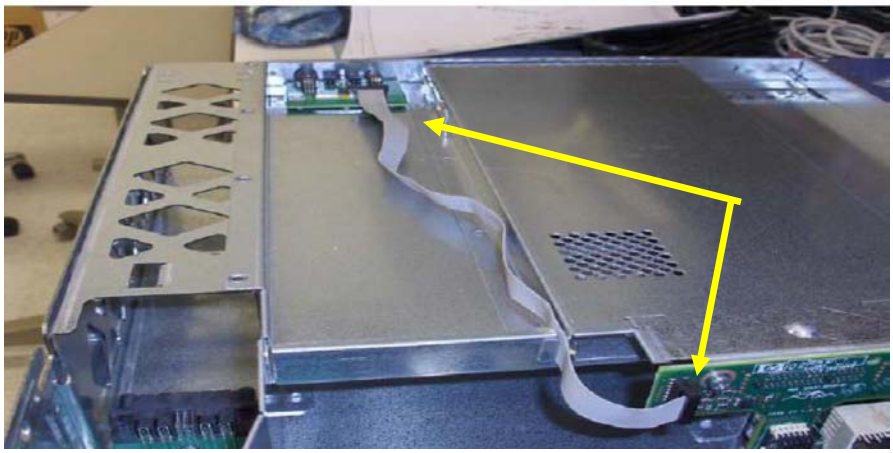


Figure 4.

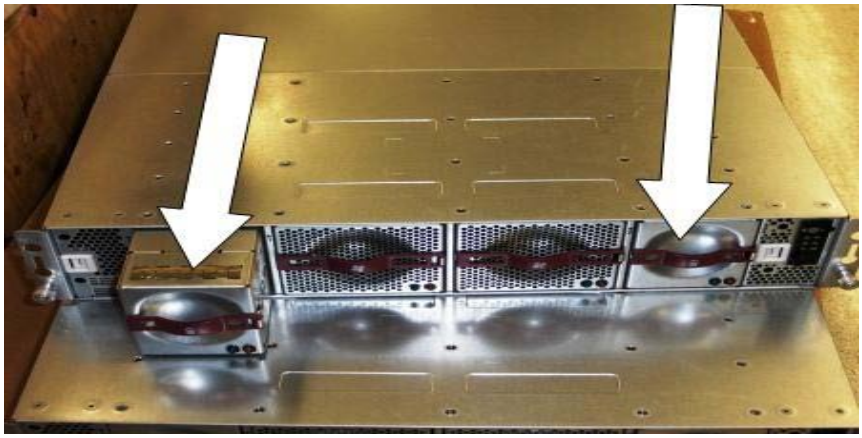


Figure 5.

Figure 6.

Figure 7.

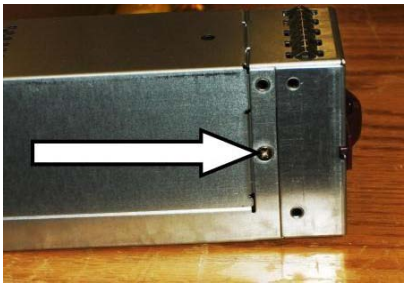


Figure 8.

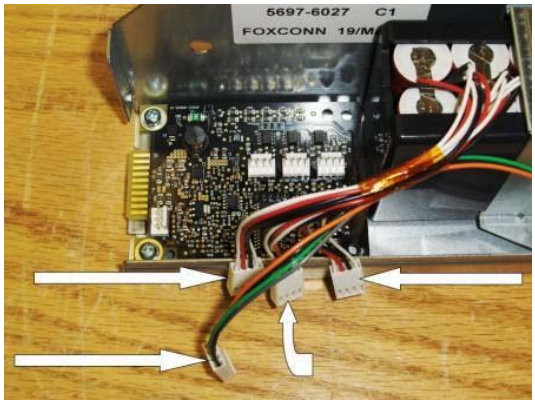


Figure 9.

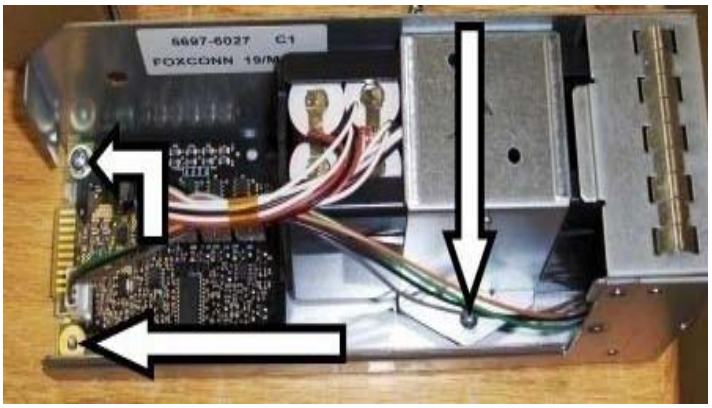


Figure 10.

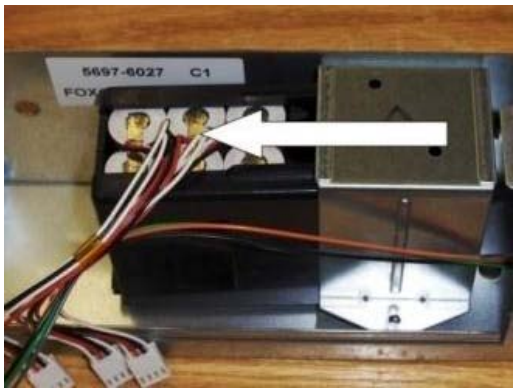
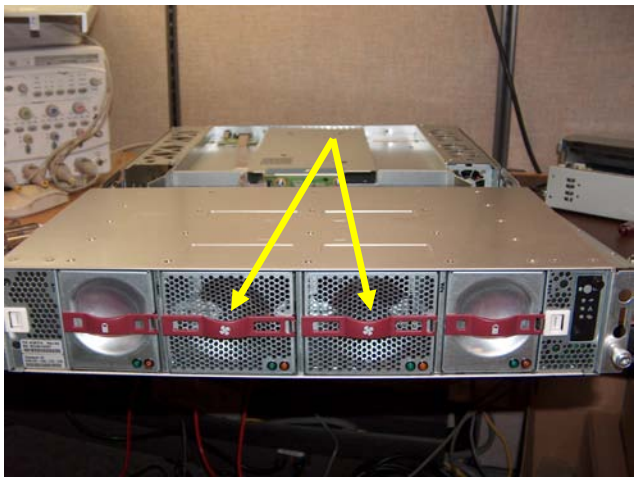


Figure 11.

Figure 12



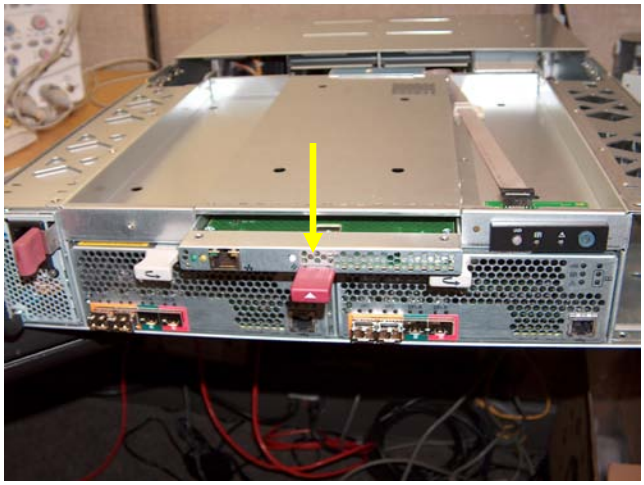


Figure 13

Figure 14

Figure 15

Figure 16.

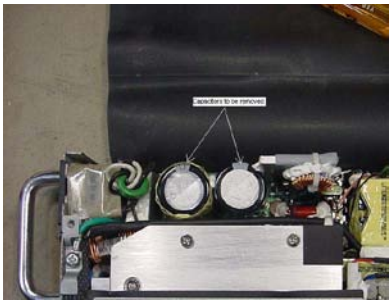
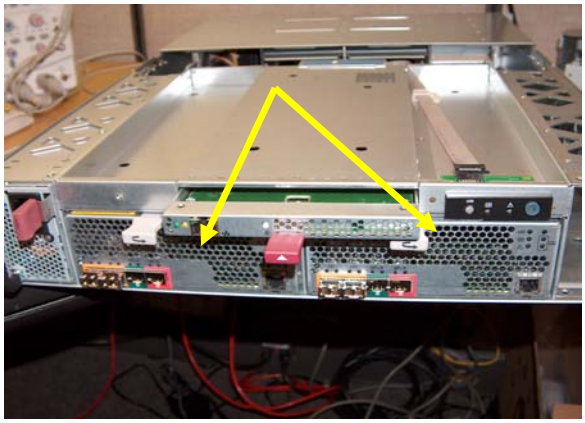


Figure 17

Figure 18



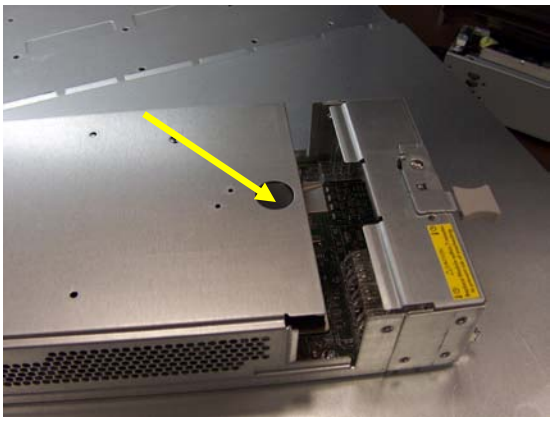


Figure 19